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DEVICE****Publication Classification**(71) Applicant: **SHENZHEN ENVICOOL
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CAI**, Shenzhen Guangdong (CN)(57) **ABSTRACT**(73) Assignee: **SHENZHEN ENVICOOL
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A cooling device includes a cooling plate and a buffer portion, a flow passage is formed in the cooling plate, and the buffer portion is arranged on the cooling plate. An inlet buffer zone and an outlet buffer portion are defined in the buffer portion, liquid flows into the flow passage through the inlet buffer zone and flows out of the flow passage through the outlet buffer portion. The liquid flows into the flow passage through the buffer portion, and the buffer portion can reduce the flow resistance of the liquid flowing into the flow passage. The liquid in the flow passage also flows out through the buffer portion, and the buffer portion can also reduce the flow resistance of the liquid flowing out of the flow passage.

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